

Title (en)

ARRANGEMENT OF ELECTRICAL CONDUCTORS AND METHOD FOR MANUFACTURING AN ARRANGEMENT OF ELECTRICAL CONDUCTORS

Title (de)

ANORDNUNG ELEKTRISCHER LEITER UND VERFAHREN ZUR HERSTELLUNG EINER ANORDNUNG ELEKTRISCHER LEITER

Title (fr)

SYSTÈME DE CONDUCTEURS ÉLECTRIQUES ET PROCÉDÉ DE FABRICATION D'UN SYSTÈME DE CONDUCTEURS ÉLECTRIQUES

Publication

**EP 3227894 A1 20171011 (DE)**

Application

**EP 15798332 A 20151123**

Priority

- DE 102014017857 A 20141203
- EP 2015002355 W 20151123

Abstract (en)

[origin: CA2967703A1] The invention relates to an arrangement of electrical conductors comprising a conductor bundle having at least one individual electrical cable and at least one cooling line through which a cooling fluid is to flow. In order to thermally connect the conductor bundle to the at least one cooling line, one section of the at least one cooling line and the conductor bundle are embedded in a metal with a low melting temperature, wherein an insulating sheath of the at least one individual cable is embodied as plastic insulation, preferably as polyimide insulation or as polyester insulation. The invention also relates to a method for manufacturing such an arrangement.

IPC 8 full level

**H01F 5/02** (2006.01); **H01B 7/42** (2006.01); **H01F 5/06** (2006.01); **H01F 27/16** (2006.01); **H01F 27/22** (2006.01); **H01F 27/28** (2006.01)

CPC (source: CN EP KR US)

**H01B 3/306** (2013.01 - CN EP KR US); **H01B 3/421** (2013.01 - CN EP KR US); **H01F 5/06** (2013.01 - CN EP US); **H01F 27/16** (2013.01 - CN EP KR US); **H01F 27/22** (2013.01 - CN EP KR US); **H01F 27/24** (2013.01 - US); **H01F 27/2823** (2013.01 - US); **H01F 27/2876** (2013.01 - CN EP KR US); **H01F 27/327** (2013.01 - US); **H01F 41/02** (2013.01 - US)

Citation (search report)

See references of WO 2016087029A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**DE 102014017857 B3 20160211**; CA 2967703 A1 20160609; CN 107210110 A 20170926; CN 107210110 B 20181109; EP 3227894 A1 20171011; EP 3227894 B1 20180822; ES 2698415 T3 20190204; JP 2018502448 A 20180125; KR 20170093858 A 20170816; PL 3227894 T3 20190430; US 2019006087 A1 20190103; WO 2016087029 A1 20160609

DOCDB simple family (application)

**DE 102014017857 A 20141203**; CA 2967703 A 20151123; CN 201580065833 A 20151123; EP 15798332 A 20151123; EP 2015002355 W 20151123; ES 15798332 T 20151123; JP 2017529988 A 20151123; KR 20177016980 A 20151123; PL 15798332 T 20151123; US 201515531570 A 20151123